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Backman(10) **Pub. No.: US 2014/0238737 A1**(43) **Pub. Date: Aug. 28, 2014**(54) **REDUCING INDUCTIVE HEATING**(52) **U.S. Cl.**(71) Applicant: **NOKIA CORPORATION**, Espoo (FI)CPC **H05K 9/002** (2013.01)USPC **174/396**(72) Inventor: **Juha Reinhold Backman**, Espoo (FI)

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ABSTRACT(73) Assignee: **Nokia Corporation**, Espoo (FI)(21) Appl. No.: **13/778,781**(22) Filed: **Feb. 27, 2013****Publication Classification**(51) **Int. Cl.****H05K 9/00**

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An audio transducer apparatus including a component having a first material; and a heating reduction system configured to reduce induced heating in the component. The heating reduction system includes a member at least partially surrounding the component. The member includes a material which has an electrical conductivity that is higher than an electrical conductivity of the first material to thereby reduce induced heating in the component.

